

HLT7000 Thermal Conductive Gel

BENEFITS AND FEATURES

- Low contact resistance
- Easy to dispense and rework
- High compressibility for low stress applications
- Long-term reliability
- Less oil separation
- No pump out and cracking

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Memory & power modules

OVERVIEW

Honeywell HLT7000 is two-part, dispensable thermally conductive gel, which offer long-term reliability and superior softness. The enhanced bonding force between the polymer base and the filler largely improves the thermally conductive gel oil separation issue in storage. Prior to curing, the material maintains good thixotropic characteristics and low viscosity to be easily dispensed. The product can be cured in short time after two-component mixing at room temperature. The high compressibility minimizes thermal resistance at interfaces, while maintaining excellent performance during reliability testing.

STORAGE & USE

- Shelf life 6 months at 0-35°C, ≤65%RH

Property	HLT7000	Test Method
Color	Part A: Dark Red Part B: Grey	Visual
Mix Ratio	1:1	by Volume
Thermal Conductivity (W/m-K)	7.0	ASTM D5470
Thermal Impedance (°C-in ² /W) (1mm@10psi, Typical Value)	0.20	ASTM D5470
Viscosity (Pa·s@25°C)	1,350	ASTM D2196 Thermo Fisher, 2s ⁻¹
Density(g/cm ³)	3.5	ASTM D792
Hardness (Shore00)	50	ASTM D2240
Working Time@25°C (min)	80.0	HON Internal
Curing Time	@23°C (h)	12.0
	@100°C (min)	3.0
Dielectric Strength (KV/mm)	8	ASTM D149
Volume Resistivity (ohm-cm)	4.0×10 ¹⁵	ASTM D257
Flammability Rating	V-0(Equivalent)	UL 94
Operating Temperature (°C)	-40~150	HON Internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102
 China: 400-840-2233
 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
 Singapore: 65-6580-3593

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